

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



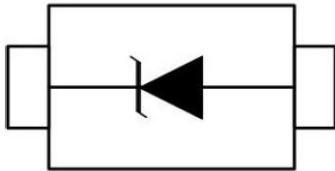
GDT



PLED

Product data sheet

- ◆ 350 Watts peak pulse power ($t_p = 8/20\mu s$)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) $\pm 15kV$ (air), $\pm 8kV$ (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 5V
- ◆ Protects one bidirectional line
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



SOD-323

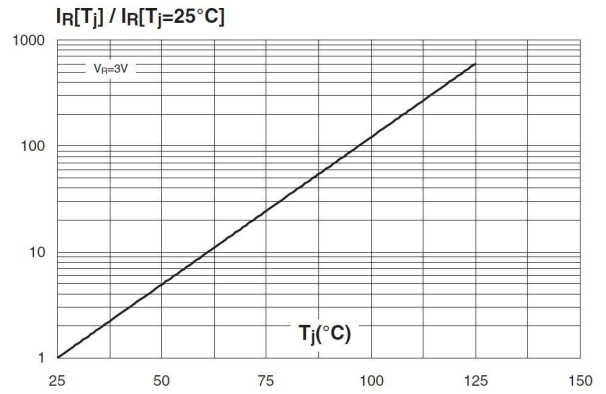
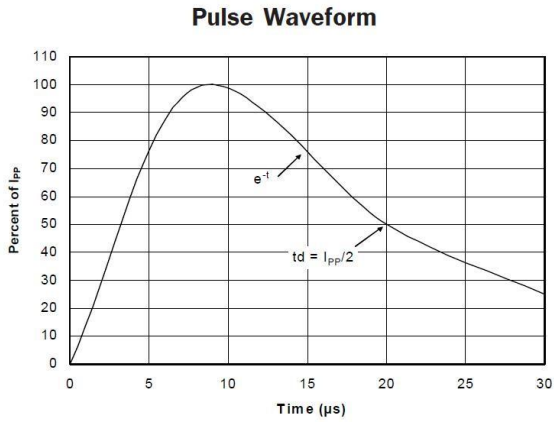
Applications

- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

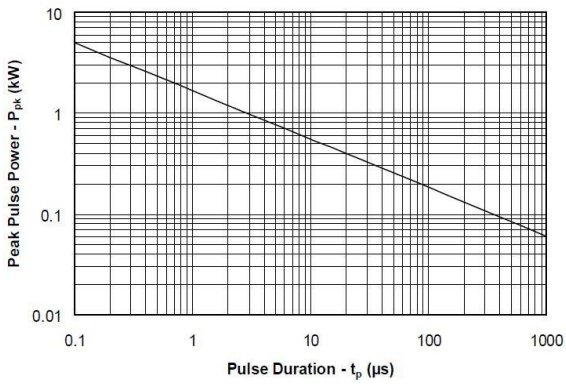
Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air)	± 15	kV
	ESD per IEC 61000-4-2 (Contact)	± 8	
P_{PP}	Peak Pulse Power (8/20 μs)	350	W
T_{OPT}	Operating Temperature	-55/+150	$^{\circ}C$
T_{STG}	Storage Temperature	-55/+150	$^{\circ}C$
T_L	Lead Soldering Temperature	260 (10 sec.)	$^{\circ}C$

P/N	V_{RWM} (V) (max.)	V_B (V) (min.)	I_T (mA)	$V_C@1A$ (V) (max.)	V_C (V) (max.) (@A)	I_R (μA) (max.)	C_T (pF) (max.)
ESD5V0D3-MS	5	6	1	9.8	18	17	300

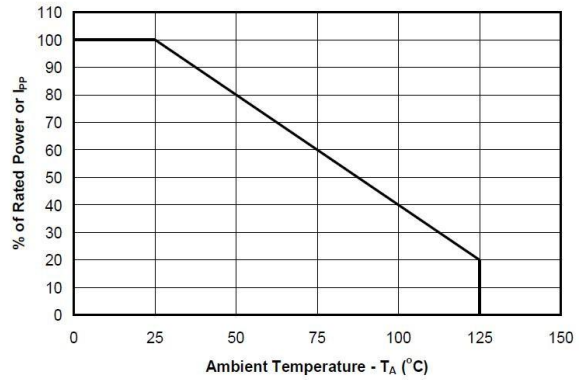
Typical Characteristics @ $T_a=25^\circ C$ unless otherwise specified



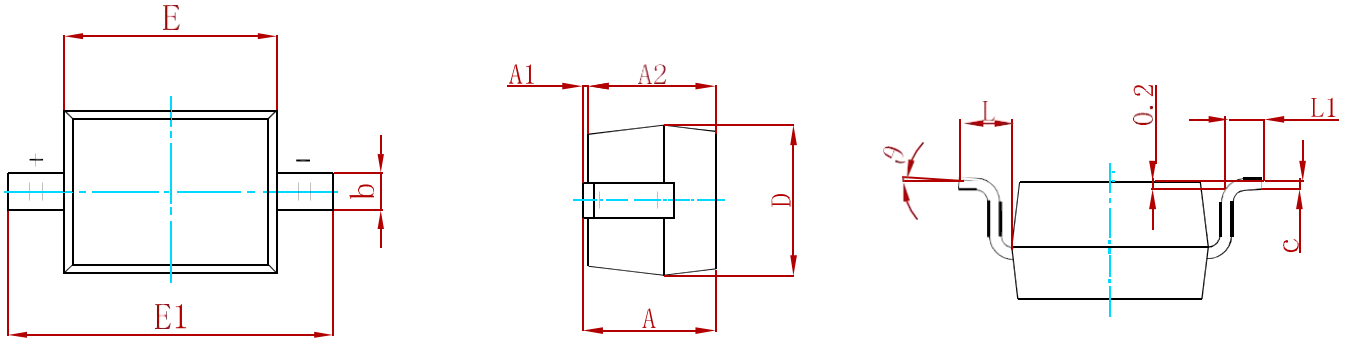
Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

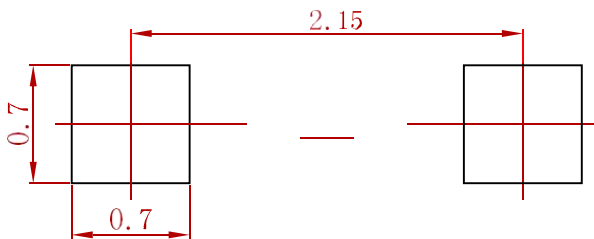


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5V0D3-MS	SOD-323	3000

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